

IN THE SPECIFICATION

Please amend the paragraph beginning at page 3, line 16 to read as follows:

A Sub B1
 - -An object is to provide internal colored markings and/or indicia on packages which cannot be [be] scraped off and replaced by different markings and/or indicia for purposes of relabeling or to cover up the original source of a product in cases of misappropriation of products. - -

Please amend the paragraph beginning at page 12 line 12 to read as follows:

Sub B2
A2
 - - FIG. 33 shows an alternative type of marking in accordance with this invention. In this case the difference is that the package P2 comprising a flip-chip (face down) CH3 has internal marking [indicia] indicia IM formed on the bottom surface (that is the active device surface) thereof. In this case the internal marking [indicia] indicia IM are protected from damage or remarking since chip CH3 is covered, at least in part, by a non-black, protection layer PL3 between elements of the BGA balls BL. Protection layer PL3 is formed directly on the lower surface (as seen in FIG. 33) of the flip-chip CH3 and on top of the internal marking indicia IM. Some chips are sensitive to light. This embodiment protects the light sensitive surface of the flip-chip CH3 from exposure to light leakage since the uncovered surface is facing the lower packaging element (not shown) which will protect the light sensitive surface of flip-chip CH3 from light. - -

IN THE CLAIMS

Please amend the claims to read as follows:

- Sub B3*
A3
 1. (Amended) A method of marking a chip having surfaces comprising the following steps:
 forming internal marking indicia on a marking location upon an exterior surface of the chip for identification of the chip, and
 forming a non-black, optically transmissive material over at least the marking location on the one exterior surface of the chip which non-black, optically transmissive material cannot be scraped off of the chip for prevention of replacement of the internal marking indicia by different markings.